

Nov. 2. 2006 3:23PM

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Date:	November 2, 2006	Fax:	571-273-8300
To:	U.S. Patent and Trademark Office	Phone:	
Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450			
From:	David C. Hsia		
Serial No.:	10/826,800		
Docket:	10030280-4		
Re:	Amendment in response to Office Action		
Pages:	7 (including cover sheet)		

Message:

Re: Applicant(s): Tanya J. Snyder, Robert H. Yi, Robert E. Wilson
Assignee: Agilent Technologies, Inc.
Title: Wafer Bonding Using Reactive Foils for Massively Parallel
Micro-Electromechanical Systems Packaging
Serial No.: 10/826,800
Examiner: David Nhu
Docket No.: 10030280-4

Filed: April 15, 2004
Group Art Unit: 2818

Dear Sir:

Transmitted herewith are the following documents in the above-identified application:

- (1) Transmittal Letter for Response/Amendment (1 page);
- (2) Amendment (5 pages).

The information contained in this message is intended only for the personal and confidential use of the designated recipient(s) named above. This message may be an attorney-client communication and may be protected by the work product doctrine. As such, this document is privileged and confidential. If the reader of this message is not the intended recipient, you are hereby notified that you have received this document in error and that any review, dissemination, distribution, or copying of this message is strictly prohibited. If you have received this communication in error, please notify us immediately by telephone and destroy any copies of this document in your possession. Thank you.

AVAGO TECHNOLOGIES, LTD.
P.O. Box 1920
Denver, Colorado 80201-1920

ATTORNEY DOCKET NO. 10030280-4

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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Inventor(s): Tanya J. Snyder et al.

Serial No.: 10/828,800

Examiner: David Nhu

Filing Date: April 15, 2004

Group Art Unit: 2818

Title: WAFER BONDING USING REACTIVE FOILS FOR MASSIVELY PARALLEL
MICRO-ELECTROMECHANICAL SYSTEMS PACKAGING

COMMISSIONER FOR PATENTS
P.O. Box 1450
Alexandria VA 22313-1450

TRANSMITTAL LETTER FOR RESPONSE/AMENDMENT

Sir:

Transmitted herewith is/are the following in the above-identified application:

- ☒ Response/Amendment ☐ Petition to extend time to respond
☐ New fee as calculated below ☐ Supplemental Declaration
☒ No additional fee (Address envelope to "Mail Stop Amendments")
☐ Other: (Fee \$_____)

CLAIMS AS AMENDED BY OTHER THAN A SMALL ENTITY						
(1) FOR	(2) CLAIMS REMAINING AFTER AMENDMENT	(3) NUMBER EXTRA	(4) HIGHEST NUMBER PREVIOUSLY PAID FOR	(5) PRESENT EXTRA	(6) RATE	(7) ADDITIONAL FEES
TOTAL CLAIMS	7	MINUS	20	= 0	X 50	\$ 0
INDEP. CLAIMS	2	MINUS	4	= 0	X 200	\$ 0
<input type="checkbox"/> FIRST PRESENTATION OF A MULTIPLE DEPENDENT CLAIM					+ 360	\$ 0
EXTENSION FEE	1 ST MONTH 120.00 <input type="checkbox"/>	2 ND MONTH 450.00 <input type="checkbox"/>	3 RD MONTH 1020.00 <input type="checkbox"/>	4 TH MONTH 1590.00 <input type="checkbox"/>		
					OTHER FEES	\$ 0
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT						\$ 0

Charge \$ 0 to Deposit Account 50-3718. At any time during the pendency of this application, please charge any fees required or credit any over payment to Deposit Account 50-3718 pursuant to 37 CFR 1.25. Additionally please charge any fees to Deposit Account 50-3718 under 37 CFR 1.16, 1.17, 1.19, 1.20 and 1.21. A duplicate copy of this transmittal letter is enclosed.

Respectfully submitted,

Tanya J. Snyder et al.

By

David C. Hsia
Attorney/Agent for Applicant(s)

I hereby certify that this paper is being facsimile
transmitted to the Patent and Trademark Office on
the date shown below:

Date of facsimile: November 2, 2006

Typed Name: David C. Hsia

Signature: 

Reg. No. 46,235

Date: November 2, 2006

Telephone No. (408) 382-0480

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

NOV 02 2006

Applicant(s): Tanya J. Snyder, Robert H. Yi, Robert E. Wilson
Assignee: Avago Technologies, Ltd.
Title: Wafer Bonding Using Reactive Foils For Massively Parallel Micro-Electromechanical Systems Packaging
Serial No.: 10/826,800 Filing Date: April 15, 2004
Examiner: David Nhu Group Art Unit: 2818
Docket No.: 10030280-4

San Jose, California
November 2, 2006

Mail Stop Amendment
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT

Dear Sir:

This is a response to the August 2, 2006 Office Action, which has a statutorily shortened period for response that ends on November 2, 2006. Please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.